Epoxy Technology EPO-TEK® 353ND-T4 Thixotropic Epoxy

Category : Polymer , Thermoset , Epoxy

Material Notes:

Product Description: EPO-TEK® 353ND-T4 is a two component, highly thixotropic epoxy with non-flowing properties and high temperature resistance. This is a higher viscosity version of EPO-TEK® 353ND-T for applications needing decreased flowAdvantages & Application Notes: Suitable for fiber optic, medical grade, circuit assembly applications.Recommended for bonding metals, glass, ceramics and many types of plastic.High temperature adhesive for hybrids and medical devices; it can resist the 300°C temperature range for long periods of time.Used in circuit assembly applications; staking SMDs to PCB, bonding ferrite cores together in copper coil windings, inductor coils and power devices; also suitable for COB glob-top DAM material.Alternative product versions available with distinct viscosity ranges Can be applied by screen printing, spatula, hand held or automatic dispensing equipment.Amber color change when properly cured for easy visual ID and inspection.Information Provided by Epoxy Technology

Order this product through the following link:
http://www.lookpolymers.com/polymer_Epoxy-Technology-EPO-TEK-353ND-T4-Thixotropic-Epoxy.php

Physical Properties	Metric	English	Comments
Specific Gravity	1.02 g/cc	1.02 g/cc	Part B
	1.11 g/cc	1.11 g/cc	Part A
Particle Size	<= 20 µm	<= 20 µm	
Viscosity	11000 - 17000 cP @Temperature 23.0 °C	11000 - 17000 cP @Temperature 73.4 °F	20 rpm

Mechanical Properties	Metric	English	Comments
Hardness, Shore D	80	80	
Tensile Modulus	3.8550 GPa	559.12 ksi	Storage
Shear Strength	>= 13.8 MPa	>= 2000 psi	Lap
	>= 35.2 MPa	>= 5100 psi	Die

Thermal Properties	Metric	English	Comments
CTE, linear	43.0 µm/m-°C	23.9 µin/in-°F	Below Tg
	231 µm/m-°C	128 µin/in-°F	Above Tg
Maximum Service Temperature, Air	225 °C	437 °F	Continuous
	325 °C	617 °F	Intermittent
Minimum Service Temperature, Air	-55.0 °C	-67.0 °F	Continuous

Thermal Properties	Metric	English	Comments
	-55.0 °C	-67.0 °F	Intermittent
Glass Transition Temp, Tg	>= 90.0 °C	>= 194 °F	Dynamic Cure 20—200°C /ISO 25 Min; Ramp 10—200°C @ 20°C/Min
Decomposition Temperature	409 °C	768 °F	Degradation Temperature

Electrical Properties	Metric	English	Comments
Volume Resistivity	>= 4.00e+12 ohm-cm	>= 4.00e+12 ohm-cm	
Dielectric Constant	3.21 @Frequency 1000 Hz	3.21 @Frequency 1000 Hz	
Dissipation Factor	0.0030 @Frequency 1000 Hz	0.0030 @Frequency 1000 Hz	

Processing Properties	Metric	English	Comments
Cure Time	1.00 min @Temperature 150 °C	0.0167 hour @Temperature 302 °F	Minimum Bond Line
	5.00 min @Temperature 120 °C	0.0833 hour @Temperature 248 °F	Minimum Bond Line
	10.0 min @Temperature 100 °C	0.167 hour @Temperature 212 °F	Minimum Bond Line
	30.0 min @Temperature 80.0 °C	0.500 hour @Temperature 176 °F	Minimum Bond Line
Pot Life	180 min	180 min	
Shelf Life	9.00 Month @Temperature 25.0 °C	9.00 Month @Temperature 77.0 °F	refrigerated

Descriptive Properties	Value	Comments
Color	Amber	Part B
	Tan	Part A
Consistency	Smooth, thixotropic paste	
Mix Ratio By Weight	10:1	
Number of Components	Two	
Thixotropic Index	2.3	

Descriptive Properties	Value	Comments
	1.22%	250°C
	2.37%	300°C

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